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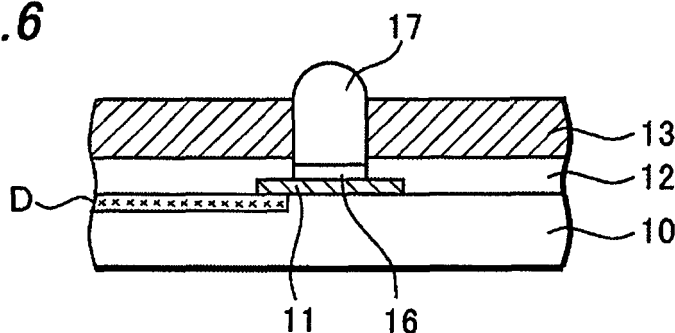
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(54) **Semiconductor device and manufacturing method of the same**

(57) The invention provides a package type semiconductor device and a manufacturing method thereof where reliability is improved without increasing a manufacturing cost. A resin layer (12) and/or a supporting member (13) are formed on a top surface of a semiconductor substrate (10) formed with pad electrodes (11). Then, openings (15) are formed penetrating the resin layer (12) and/or the supporting member (13) so as to expose the pad

electrodes (11). Metal layers (16) are then formed on the pad electrodes (11) exposed in the openings (15), and conductive terminals (17) are formed thereon. Finally, the semiconductor substrate (10) is separated into semiconductor dice by dicing. When this semiconductor device is mounted on a circuit board, the conductive terminals (17) of the semiconductor die and external electrodes of the circuit board are electrically connected with each other.

FIG.6





EUROPEAN SEARCH REPORT

Application Number
EP 05 01 2443

DOCUMENTS CONSIDERED TO BE RELEVANT			
Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (IPC)
X	US 2002/153581 A1 (LIN HONG-MING [TW] ET AL) 24 October 2002 (2002-10-24) * abstract * * paragraphs [0019], [0020] * * claims 1-4 * * figure 4 *	1-24	INV. H01L31/0203 H01L23/31
X	US 2002/110949 A1 (TONTI WILLIAM R [US] ET AL) 15 August 2002 (2002-08-15) * abstract * * paragraphs [0066], [0067] * * paragraphs [0070] - [0073] * * figures 9-11 * * paragraphs [0061] - [0064] *	1-24	
X	US 2004/023433 A1 (ERIKSON KENNETH R [US] ET AL) 5 February 2004 (2004-02-05) * abstract * * paragraphs [0031], [0035], [0037], [0038], [0040], [0041], [0046], [0052], [0056]; figures 1a, 1b, 2a, 3a, 4a, 5a, 6a, 7a, 8a, 9a, 10a *	1-24	
The present search report has been drawn up for all claims			TECHNICAL FIELDS SEARCHED (IPC) H01L
Place of search Berlin		Date of completion of the search 3 December 2008	Examiner Morena, Enrico
CATEGORY OF CITED DOCUMENTS X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document		T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application L : document cited for other reasons & : member of the same patent family, corresponding document	

3
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**ANNEX TO THE EUROPEAN SEARCH REPORT
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EP 05 01 2443

This annex lists the patent family members relating to the patent documents cited in the above-mentioned European search report.
The members are as contained in the European Patent Office EDP file on
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